

AMENDMENTS TO THE CLAIMS

Following is a listing of all claims in the present application, which listing supersedes all previously presented claims:

Listing of Claims:

Claims 1-14. (Canceled).

15. (Currently Amended) A method of a photolithography processing system, comprising:

illuminating a surface of a wafer supported by a table with first illumination tools and a second ~~illuminating tools~~ illumination tool by positioning the first illumination tools at varying lateral heights relative to the table to illuminate the surface of the wafer at various predetermined angles of incidence and positioning the second illumination tool to illuminate the surface of the wafer vertically from above the wafer on the table;

taking pictures of the surface of the wafer with a camera while the surface of the wafer is being illuminated;

receiving a signal from the camera in a controller;

detecting a presence of particles on the surface of the wafer with the controller; and

transporting the wafer to the process-performing or cleaning position according to whether particles are detected on the surface of the wafer.

16. (Canceled).

17. (Original) The method of a photolithography processing system as claimed in claim 15, wherein the taking of pictures of the surface of the wafer comprises:

obtaining a first image while the first illumination tools are maintained in an 'on' position and the second illumination tool is maintained in an 'off' position;

obtaining a second image while the first illumination tools are maintained in an 'off' position and the second illumination tool is maintained in an 'on' position; and

forming a multi-dimensional image by combining the first and second images.

18. (New) The method of a photolithography processing system as claimed in claim 15, wherein positioning the first illumination tools at varying lateral heights relative to the table to illuminate the surface of the wafer at various predetermined angles of incidence comprises positioning the first illumination tools to have an angle of incidence varying between 0° and approximately 70°.

19. (New) The method of a photolithography processing system as claimed in claim 15, further comprising controlling the angle of incidence of the first illumination tools in accordance with an illumination control signal.

20. (New) The method of a photolithography processing system as claimed in claim 15, further comprising altering the lateral height of the first illumination tools in accordance with an illumination control signal.

21. (New) The method of a photolithography processing system as claimed in claim 15, wherein the second illumination tool is positioned around the camera.

22. (New) The method of a photolithography processing system as claimed in claim 15, wherein the first illumination tools are positioned on both sides of the table to allow various changes in height for illuminating at an angle of incidence; and the second illumination tool vertically illuminates the surface of the wafer from the top of the table.

23. (New) The method of a photolithography processing system as claimed in claim 15, further comprising rotating the table in response to a control signal to thereby rotate a position of the wafer in response to angles of incidence of the first illumination tools and the second illumination tool.